



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Application of:

Madhav Datta

Group Art Unit: 2829

Serial No.: 10/688,418

Examiner: Karlsen, Ernest F.

Filed: Oct. 17, 2003

In Response to Office Action  
Dated: Oct. 5, 2004

For: Method for Testing Chips on Flat Solder Bumps

Attorney Docket No.: 64,610-042A (YO998-431US2)

Certificate of Mailing

I hereby certify that this paper (along with any referred to as being attached or enclosed) is being deposited with the United States Postal Service on the date shown below with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Kathy Dixon

Date: Nov. 5, 2004

**RESPONSE TO OFFICE ACTION**

Commissioner for Patents  
Alexandria, VA 22313-1450

Dear Sir:

In response to an Office Action mailed Oct. 5, 2004,  
please consider the following remarks.